## **AMENDMENTS TO THE CLAIMS**

1. (Currently Amended) A semiconductor device LED (light-emitting diode device) comprising:

a substrate provided with a region of the back surface having concentrated dislocations at least on part of the back surface thereof;

a semiconductor element layer formed on the front surface of said substrate;

an insulator film formed on said region of the back surface having said concentrated dislocations; and

a back electrode formed to be in contact with a region of the back surface of said substrate other than said region of the back surface having said concentrated dislocations, wherein

the back electrode is a transparent electrode.

2. (Currently Amended) The semiconductor device <u>LED</u> according to claim 1, wherein

said semiconductor element layer is provided with a region of the front surface having said concentrated dislocations at least on part of the front surface thereof,

said semiconductor device further comprising a front electrode formed to be in contact with a region of the front surface of said semiconductor element layer other than said region of the front surface having said concentrated dislocations.

3. (Currently Amended) The semiconductor device LED according to claim 1, wherein